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Miljötålighetsprovning – Del 2-20: Provningsmetoder – Ta och Tb: Lödbarhet och lödtålighet

Environmental testing –

Part 2-20: Tests –

Test Ta and Tb: Test methods for solderability and resistance to soldering heat of devices with leads

Som svensk standard gäller europastandarden EN IEC 60068-2-20:2021. Den svenska standarden innehåller den officiella engelska språkversionen av EN IEC 60068-2-20:2021.

Nationellt förord

Europastandarden EN IEC 60068-2-20:2021

består av:

- **europastandardens ikraftsättningsdokument**, utarbetat inom CENELEC
- **IEC 60068-2-20, Sixth edition, 2021 - Environmental testing - Part 2-20: Tests - Test Ta and Tb: Test methods for solderability and resistance to soldering heat of devices with leads**

utarbetad inom International Electrotechnical Commission, IEC.

Tidigare fastställd svensk standard SS-EN 60068-2-20, utgåva 1, 2009, gäller ej fr o m 2024-05-04.

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English Version

**Environmental testing - Part 2-20: Tests - Test Ta and Tb: Test
methods for solderability and resistance to soldering heat of
devices with leads
(IEC 60068-2-20:2021)**

Essais d'environnement - Partie 2-20: Essais - Essais Ta et
Tb: Méthodes d'essai de la brasabilité et de la résistance à
la chaleur de brasage des dispositifs à broches
(IEC 60068-2-20:2021)

Umgebungseinflüsse - Teil 2-20: Prüfungen - Prüfung Ta
und Tb: Prüfverfahren für die Lötbarkeit und
Lötwärmebeständigkeit von Bauelementen mit
herausgeführten Anschlüssen
(IEC 60068-2-20:2021)

This European Standard was approved by CENELEC on 2021-05-04. CENELEC members are bound to comply with the CEN/CENELEC Internal Regulations which stipulate the conditions for giving this European Standard the status of a national standard without any alteration.

Up-to-date lists and bibliographical references concerning such national standards may be obtained on application to the CEN-CENELEC Management Centre or to any CENELEC member.

This European Standard exists in three official versions (English, French, German). A version in any other language made by translation under the responsibility of a CENELEC member into its own language and notified to the CEN-CENELEC Management Centre has the same status as the official versions.

CENELEC members are the national electrotechnical committees of Austria, Belgium, Bulgaria, Croatia, Cyprus, the Czech Republic, Denmark, Estonia, Finland, France, Germany, Greece, Hungary, Iceland, Ireland, Italy, Latvia, Lithuania, Luxembourg, Malta, the Netherlands, Norway, Poland, Portugal, Republic of North Macedonia, Romania, Serbia, Slovakia, Slovenia, Spain, Sweden, Switzerland, Turkey and the United Kingdom.



European Committee for Electrotechnical Standardization
Comité Européen de Normalisation Electrotechnique
Europäisches Komitee für Elektrotechnische Normung

CEN-CENELEC Management Centre: Rue de la Science 23, B-1040 Brussels

European foreword

The text of document 91/1701/FDIS, future edition 6 of IEC 60068-2-20, prepared by IEC/TC 91 "Electronics assembly technology" was submitted to the IEC-CENELEC parallel vote and approved by CENELEC as EN IEC 60068-2-20:2021.

The following dates are fixed:

- latest date by which the document has to be implemented at national level by publication of an identical national standard or by endorsement (dop) 2022-02-04
- latest date by which the national standards conflicting with the document have to be withdrawn (dow) 2024-05-04

This document supersedes EN 60068-2-20:2008 and all of its amendments and corrigenda (if any).

Attention is drawn to the possibility that some of the elements of this document may be the subject of patent rights. CENELEC shall not be held responsible for identifying any or all such patent rights.

Endorsement notice

The text of the International Standard IEC 60068-2-20:2021 was approved by CENELEC as a European Standard without any modification.

In the official version, for Bibliography, the following notes have to be added for the standards indicated:

IEC 60068-2-58 NOTE Harmonized as EN 60068-2-58

IEC 60068-2-69:2017 NOTE Harmonized as EN 60068-2-69:2017 (not modified)

IEC 61190-1-3:2017 NOTE Harmonized as EN IEC 61190-1-3:2018 (not modified)

Annex ZA (normative)

Normative references to international publications with their corresponding European publications

The following documents are referred to in the text in such a way that some or all of their content constitutes requirements of this document. For dated references, only the edition cited applies. For undated references, the latest edition of the referenced document (including any amendments) applies.

NOTE 1 Where an International Publication has been modified by common modifications, indicated by (mod), the relevant EN/HD applies.

NOTE 2 Up-to-date information on the latest versions of the European Standards listed in this annex is available here: www.cenelec.eu.

<u>Publication</u>	<u>Year</u>	<u>Title</u>	<u>EN/HD</u>	<u>Year</u>
IEC 60068-1	-	Environmental testing - Part 1: General and guidance	EN 60068-1	-
IEC 60068-2-2	-	Environmental testing - Part 2-2: Tests - Test B: Dry heat	EN 60068-2-2	-
IEC 60068-2-66	-	Environmental testing - Part 2: Test methods - Test Cx: Damp heat, steady state (unsaturated pressurized vapour)	EN 60068-2-66	-
IEC 60068-2-78	-	Environmental testing - Part 2-78: Tests - Test Cab: Damp heat, steady state	EN 60068-2-78	-
IEC 61191-3	-	Printed board assemblies - Part 3: Sectional specification - Requirements for through-hole mount soldered assemblies	EN 61191-3	-
IEC 61191-4	-	Printed board assemblies - Part 4: Sectional specification - Requirements for terminal soldered assemblies	EN 61191-4	-

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INTERNATIONAL ELECTROTECHNICAL COMMISSION

ENVIRONMENTAL TESTING –

**Part 2-20: Tests –
Tests Ta and Tb: Test methods for solderability
and resistance to soldering heat of devices with leads**

FOREWORD

- 1) The International Electrotechnical Commission (IEC) is a worldwide organization for standardization comprising all national electrotechnical committees (IEC National Committees). The object of IEC is to promote international co-operation on all questions concerning standardization in the electrical and electronic fields. To this end and in addition to other activities, IEC publishes International Standards, Technical Specifications, Technical Reports, Publicly Available Specifications (PAS) and Guides (hereafter referred to as "IEC Publication(s)"). Their preparation is entrusted to technical committees; any IEC National Committee interested in the subject dealt with may participate in this preparatory work. International, governmental and non-governmental organizations liaising with the IEC also participate in this preparation. IEC collaborates closely with the International Organization for Standardization (ISO) in accordance with conditions determined by agreement between the two organizations.
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IEC 60068-2-20 has been prepared by IEC technical committee 91: Electronics assembly technology. It is an International Standard.

This sixth edition cancels and replaces the fifth edition published in 2008. This sixth edition constitutes a technical revision.

This edition includes the following significant technical changes with respect to the previous edition:

- a) update of and clarification of pre-conditioning (former "aging") and its relation to natural aging.

The text of this International Standard is based on the following documents:

Draft	Report on voting
91/1701/FDIS	91/1711/RVD

Full information on the voting for its approval can be found in the report on voting indicated in the above table.

The language used for the development of this International Standard is English.

This document was drafted in accordance with ISO/IEC Directives, Part 2, and developed in accordance with ISO/IEC Directives, Part 1 and ISO/IEC Directives, IEC Supplement, available at www.iec.ch/members_experts/refdocs. The main document types developed by IEC are described in greater detail at www.iec.ch/standardsdev/publications.

A list of all the parts in the IEC 60068 series, under the general title *Environmental testing*, can be found on the IEC website.

The committee has decided that the contents of this document will remain unchanged until the stability date indicated on the IEC website under "<http://webstore.iec.ch>" in the data related to the specific document. At this date, the document will be

- reconfirmed,
- withdrawn,
- replaced by a revised edition, or
- amended.

ENVIRONMENTAL TESTING –

Part 2-20: Tests – Tests Ta and Tb: Test methods for solderability and resistance to soldering heat of devices with leads

1 Scope

This part of IEC 60068 outlines Tests Ta and Tb, applicable to devices with leads and leads themselves. Soldering tests for surface mounting devices (SMD) are described in IEC 60068-2-58.

This document provides procedures for determining the solderability and resistance to soldering heat of devices in applications using solder alloys, which are eutectic or near eutectic tin lead (Pb), or lead-free alloys.

The procedures in this document include the solder bath method and soldering iron method.

The objective of this document is to ensure that component lead or termination solderability meets the applicable solder joint requirements of IEC 61191-3 and IEC 61191-4. In addition, test methods are provided to ensure that the component body can be resistant to the heat load to which it is exposed during soldering.

NOTE Information about wetting time and wetting force can be obtained by test methods using a wetting balance. IEC 60068-2-69 (solder bath and solder globule method) can be consulted.

2 Normative references

The following documents are referred to in the text in such a way that some or all of their content constitutes requirements of this document. For dated references, only the edition cited applies. For undated references, the latest edition of the referenced document (including any amendments) applies.

IEC 60068-1, *Environmental testing – Part 1: General and guidance*

IEC 60068-2-2, *Environmental testing – Part 2-2: Tests – Test B: Dry heat*

IEC 60068-2-66, *Environmental testing – Part 2: Test methods – Test Cx: Damp heat, steady state (unsaturated pressurized vapour)*

IEC 60068-2-78, *Environmental testing – Part 2-78: Tests – Test Cab: Damp heat, steady state*

IEC 61191-3, *Printed board assemblies – Part 3: Sectional specification – Requirements for through-hole mount soldered assemblies*

IEC 61191-4, *Printed board assemblies – Part 4: Sectional specification – Requirements for terminal soldered assemblies*